**Product data sheet** 

# 1. General description

Silicon Carbide Schottky diode in a IITO220-2L plastic package, designed for high frequency switched-mode power supplies.



### 2. Features and benefits

- · Highly stable switching performance
- · Extremely fast reverse recovery time
- · Superior in efficiency to Silicon Diode alternatives
- · Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant

# 3. Applications

- · Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

## 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage				650		V
$I_{F(AV)}$	average forward current	$\delta$ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 109 °C; Fig. 1; Fig. 2; Fig. 3			6		Α
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.45	1.70	V
		I <sub>F</sub> = 6 A; T <sub>i</sub> = 150 °C; <u>Fig. 5</u>		-	1.80	2.20	V

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		K — A
2	А	anode		001aaa020
mb	n.c.	mounting base; isolated		
			{} {}	
			Î Ž	

# 6. Ordering information

## **Table 3. Ordering information**

Type number	Package	Orderable part number	3	Small packing		Package
	name		method	quantity	version	issue date
WNSC5D06650Y	IITO220-2L	WNSC5D06650Y6Q	Tube	50	IITO220P-2L	13-Mar-2023

# 7. Marking

### **Table 4. Marking codes**

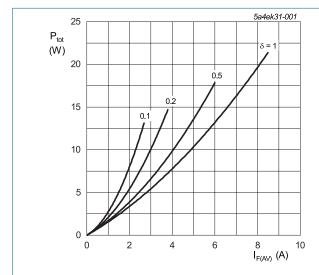
Type number	Marking codes
WNSC5D06650Y	WNSC5D 06650Y

# 8. Limiting values

### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
I <sub>F(AV)</sub>	average forward current	$δ$ = 0.5; square-wave pulse; $T_{mb} \le 109$ °C; Fig. 1; Fig. 2; Fig. 3		6	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 109 °C; square-wave pulse		12	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		36	А
	forward current	t <sub>p</sub> = 10 μs; T <sub>j(init)</sub> = 25 °C; square-wave pulse		375	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		6.48	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature			-55 to 175	°C
T <sub>j</sub>	junction temperature			-55 to 175	°C



$$\begin{split} I_{\text{F(AV)}} &= I_{\text{F(RMS)}} \times \sqrt{\delta} \\ V_{\text{o}} &= 1.426 \text{ V; } R_{\text{s}} = 0.1289 \text{ } \Omega \end{split}$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

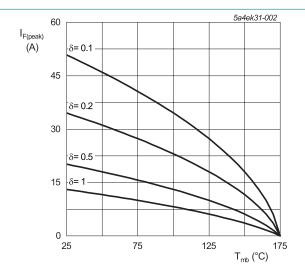
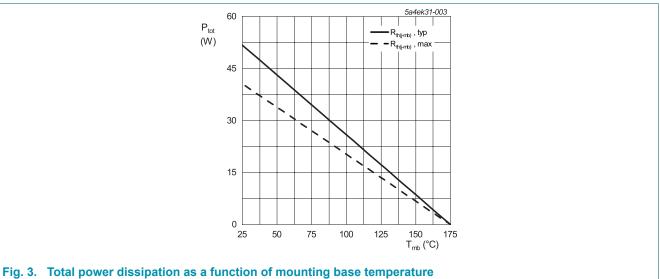


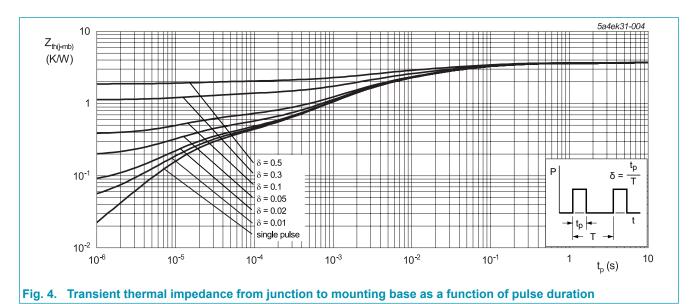
Fig. 2. Current derating as a function of mounting base temperature



## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4		-	2.9	3.7	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W



## 10. Isolation characteristics

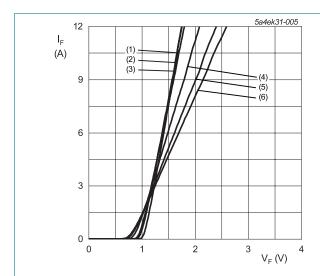
**Table 7. Isolation characteristics** 

Symbo	I Parameter	Conditions	Notes	Min	Тур	Max	Unit
V <sub>isol(RMS</sub>	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz $\leq$ f $\leq$ 60 Hz; T <sub>h</sub> = 25 °C; RH $\leq$ 65 %		-	-	2500	V

# 11. Characteristics

**Table 8. Characteristics** 

	December	Conditions	Notes	Min	Trees	May	1 I mile
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics						
$V_{F}$	forward voltage	I <sub>F</sub> = 6 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.45	1.70	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.80	2.20	V
		I <sub>F</sub> = 6 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	2.00	2.30	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	0.3	30	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>		-	15	150	μA
Dynamic	characteristics						
$Q_r$	recovered charge	$I_F = 6 \text{ A}$ ; $V_R = 400 \text{ V}$ ; $dI_F/dt = 500 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$ ; Fig. 7		-	9	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	223	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	24	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	22	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	$I_R = 3.5 \text{ A}; T_{j(init)} = 25 \text{ °C}; L = 5 \text{ mH}$		30	-	-	mJ



 $V_0 = 1.426 \text{ V}; R_s = 0.1289 \Omega$ 

(1) T<sub>i</sub> = -55 °C; typical values

(2) T<sub>i</sub> = 0 °C; typical values

(3) T<sub>i</sub> = 25 °C; typical values

(4) T<sub>j</sub> = 100 °C; typical values (5) T<sub>j</sub> = 150 °C; typical values (6) T<sub>j</sub> = 175 °C; typical values

Fig. 5. Forward current as a function of forward

voltage; typical values

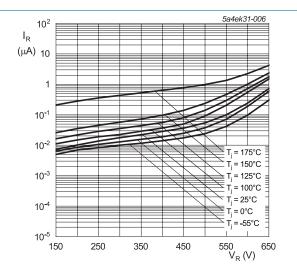
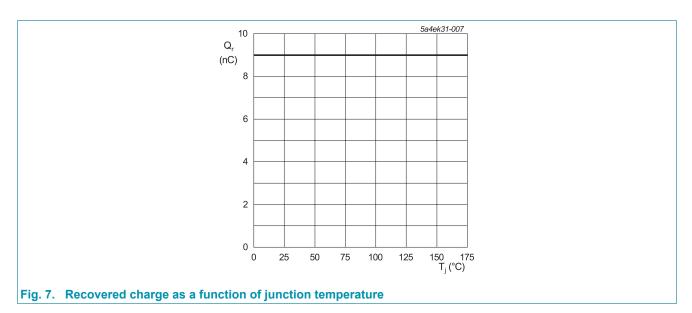
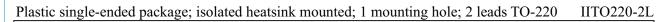
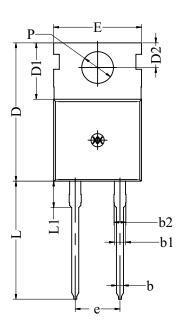


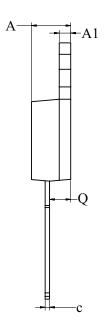
Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

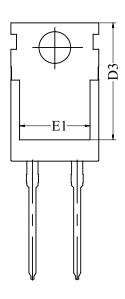


# 12. Package outline









Dim	All Dir	nensions in N	Illimeters
Dilli	Min Typ		Max
A	4.30	4.45	4.70
A1	1.25	1.30	1.40
b	0.60	0.80	0.90
bl	1.10	1.27	1.40
b2	1.32	1.37	1.72
с	0.40	0.50	0.60
D	15.20	15.70	16.00
D1	6.20	6.40	6.60
D2	2.70	2.80	3.00
D3	12.98	13.28	13.58
Е	9.70	10.00	10.30
E1	7.50	8.00	8.50
e		5.08(BSC)	
L	12.80	13.40	14.00
L1	2.80	3.00	3.20
P	3.50	3.60	3.70
Q	2.20	2.40	2.60

## 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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## 14. Contents

1. General description	1
2. Features and benefits	1
3. Applications	1
4. Quick reference data	1
5. Pinning information	2
6. Ordering information	2
7. Marking	
8. Limiting values	
9. Thermal characteristics	5
10. Isolation characteristics	5
11. Characteristics	
12. Package outline	8
13. Legal information	
14. Contents	

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